



CMS80F253x Datasheet

Enhanced flash memory 8-bit 1T 8051 microcontrollers

Rev.1.0.5

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1. Product features

1.1 Features

- ◆ **Compatible with MCS-51 1T instruction system**
 - The system clock frequency supports up to 48MHz
 - The fastest machine cycle supports $1T_{SYS} @ F_{SYS} \leq 24\text{MHz}$
 - The fastest machine cycle supports $2T_{SYS} @ F_{SYS} = 48\text{MHz}$
- ◆ **Memory**
 - program FLASH:32Kx8Bit
 - Data FLASH:1Kx8Bit
 - General RAM:256x8Bit
 - General XRAM:2Kx8Bit
 - Support BOOT function area, 1K/2K/4K optional
 - Program FLASH supports partition protection
- ◆ **4 oscillation modes**
 - HSI- Internal high-speed oscillation:48MHz
 - HSE- External high-speed oscillation: 8MHz/16MHz
 - LSE- External low-speed oscillator:32.768KHz
 - LSI- Internal low-speed oscillator:125KHz
- ◆ **GPIO**
 - Up to 30 GPIO
 - All support up/down resistance function
 - All support edge (rising edge/ falling edge/ double edge) interrupt
 - Support wake-up function
- ◆ **Interrupt source**
 - Support all external port interrupts
 - 7 timer interrupts
 - Other peripheral interrupts
- ◆ **Timer**
 - WDT wake-up (watchdog timer)
 - Timer0/1, Timer2, Timer3/4
 - LSE_Timer (Support sleep wake function)
 - WUT (wake-up wake-up)
 - BRT (Serial port baud rate clock generator)
- ◆ **Cyclic redundancy check**
 - CRC16 (CRC16-CCITT)
- ◆ **Operating voltage range**
 - 2.1V~5.5V
- ◆ **Operating temperature range**
 - -40°C~105°C
- ◆ **Low voltage reset function (LVR)**
 - 1.8V/ 2.0V/ 2.5V/ 3.5V
- ◆ **Low-voltage detection function (LVD)**
 - 2.0V~4.3V 8 levels optional
- ◆ **High-precision 12-bit ADC**
 - Up to 30 AD external channels
 - Optional reference voltage (1.2V/ 2.0V/ 2.4V/ 3.0V/ VDD)
 - Can detect internal 1.2V reference voltage
 - Support hardware trigger start conversion function
 - Support a set of result digital comparison function
- ◆ **Buzzer driver**
 - 50% duty cycle, frequency can be set freely
- ◆ **PWM**
 - 6 channels PWM
 - 6 mutually independent cycle counters
 - Support independent /complementary/ synchronous/ group mode
 - Support edge alignment
 - Support complementary mode dead zone delay function
- ◆ **Communication modules**
 - 1 x SPI (communication rate up to 6Mb/s)
 - 1 x I2C (communication rate up to 400Kb/s)
 - 2 x UART (baud rate up to 1Mb/s)
 - UART1 can be mapped to any GPIO
- ◆ **Low power mode**
 - Idle mode (IDLE)
 - Sleep mode (STOP)
- ◆ **Support 96-bit unique ID number (UID)**
 - Each chip has an independent ID number
- ◆ **Support two-wire serial programming and debugging**

1.2 Product comparison

Product mode		CMS80F2538	CMS80F2539
Peripheral interface			
Maximum clock frequency		Fsys=48MHz, Fcpu=24MHz	
Storage module	APROM	32/31/30/28 KB ⁽¹⁾	
	BOOT	0/1/2/4 KB ⁽¹⁾	
	Data FLASH	1 KB	
	RAM	256 B	
	XRAM	2 KB	
Timer	WDT	1	
	Timer0/1	2 (16bit)	
	Timer2	1 (16bit)	
	Timer3/4	2 (16bit)	
	LSE_Timer	1 (16bit)	
	WUT	1 (12bit)	
	BRT	1 (16bit)	
Enhanced Digital peripherals	CRC	CRC16-CCITT	
	BUZZER	1	
	PWM	6(16bit)	
Display Interface	LED	4COM x 22SEG、5COM x 21SEG	4COM x 22SEG、5COM x 21SEG
		6COM x 20SEG、8COM x 18SEG	6COM x 20SEG、8COM x 18SEG
Communication module	SPI	1	
	I2C	1	
	UART	2	
Analog module	12bit-ADC (Ex. Channels)	26	30
GPIOs		26	30
LVR		1.8V/2.0V/2.5V/3.5V	
LVD		2.0~4.3V, 8 levels	
Operating voltage		2.1~5.5 V	
Operating temperature		-40~105°C	
Encapsulation		SOP28	LQFP32

Note: Set the size of APROM and BOOT space through the system configuration register, the maximum total of APROM and BOOT space is 32K

2. System overview

2.1 System Introduction

The CMS80F253x series is an 8051 core, a 1T instruction system compatible with MCS-51, and a general IO type 8-bit chip. The operating frequency can reach up to 48MHz. The MCU has the following characteristics:

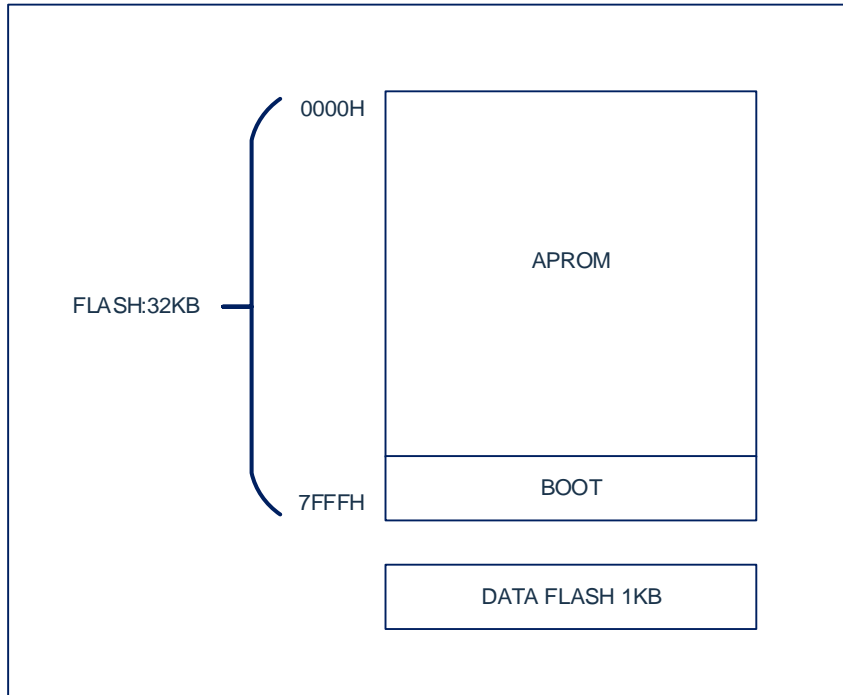
- With a maximum of 32KB program area, 256B RAM space, 2KB XRAM, 1KB non-volatile data area.
- There are four oscillation modes, the system clock can be freely switched between the three clock sources (mutual switching between HSE and LSE is prohibited), and the external oscillator stops oscillation detection.
- It supports three working modes: normal, idle, and sleep, which can effectively reduce power consumption.
- Built-in low-voltage reset LVR, low-voltage monitoring LVD, watchdog overflow reset and other protection settings, can effectively improve the reliability of system operation.
- With multiple interrupt sources such as external interrupts, timed interrupts and other peripheral interrupts, it can respond to external events in a timely manner and improve the utilization of the MCU.
- Up to 9 timers, which can realize functions such as timing, counting, input capture, output comparison, timing wake-up, and baud rate generator
- With cyclic redundancy check unit CRC
- 6-channel 16-bit PWM, supports independent, complementary, and synchronous three-mode output, and has dead zone control function.
- With 1 I2C, 1 SPI, and 2 UART communication modules, it can realize data transmission between the system and other devices.
- It has a high-precision 12-bit ADC and can choose an internal reference voltage.

2.2 Memory structure

2.2.1 Program memory FLASH

This series has a maximum of 32KB of FLASH storage space, APROM area and BOOT area share the entire FLASH space.

The block diagram of the FLASH space allocation structure is as follows:

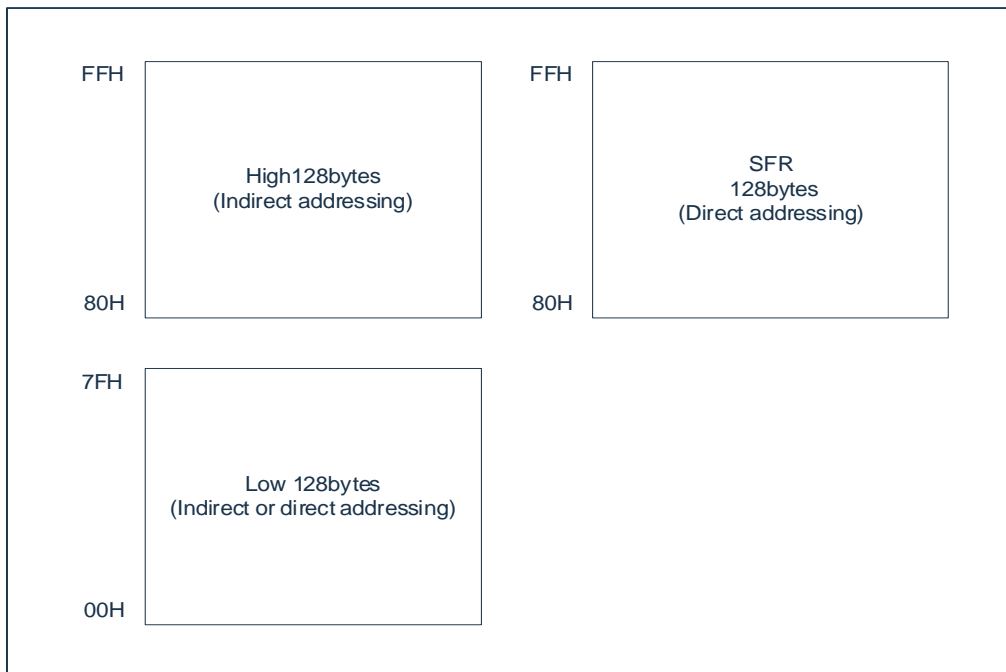


The size of BOOT can be configured, the configuration method is as follows:

Address space allocation method	32K (Program storage area)			
	APROM area		BOOT area	
method 0	32K	0000H-7FFFH	--	--
method 1	31K	0000H-7BFFH	1K	7C00H-7FFFH
method 2	30K	0000H-77FFH	2K	7800H-7FFFH
method 3	28K	0000H-6FFFH	4K	7000H-7FFFH

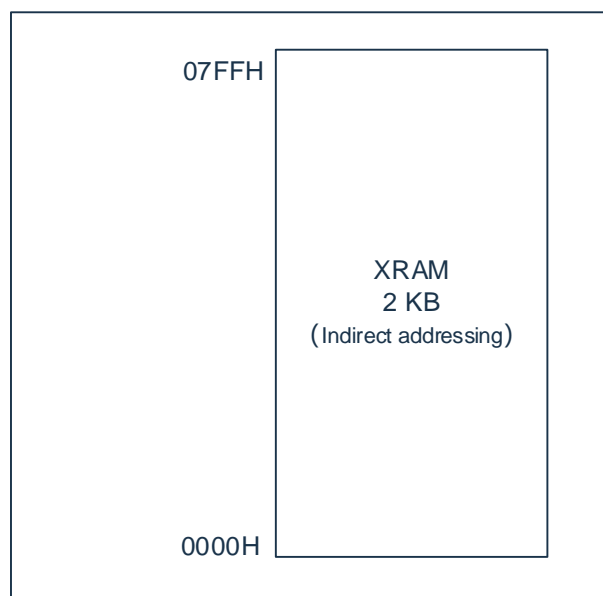
2.2.2 Internal data memory RAM

The internal data memory is divided into 3 parts: low 128Bytes, high 128Bytes, SFR. The structure diagram of RAM space allocation is shown in the figure below:



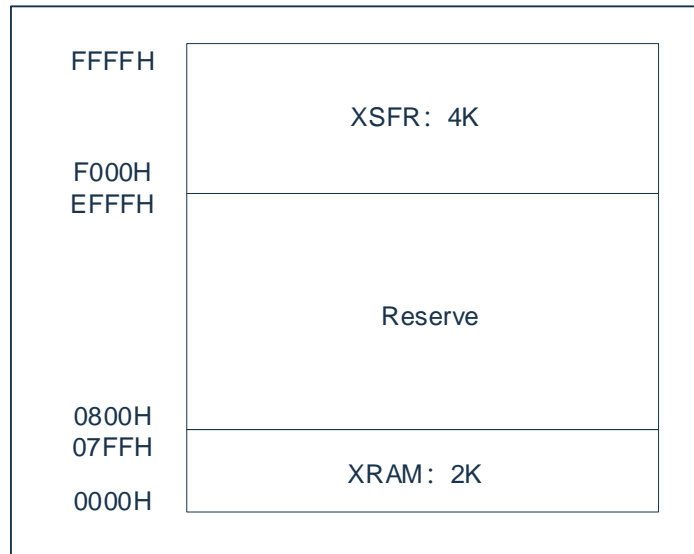
2.2.3 External data memory XRAM

There is a maximum 2KB XRAM area inside the chip, which is not related to RAM/FLASH. The structure diagram of XRAM space allocation is shown in the figure below.



2.2.4 Special function register XSFR

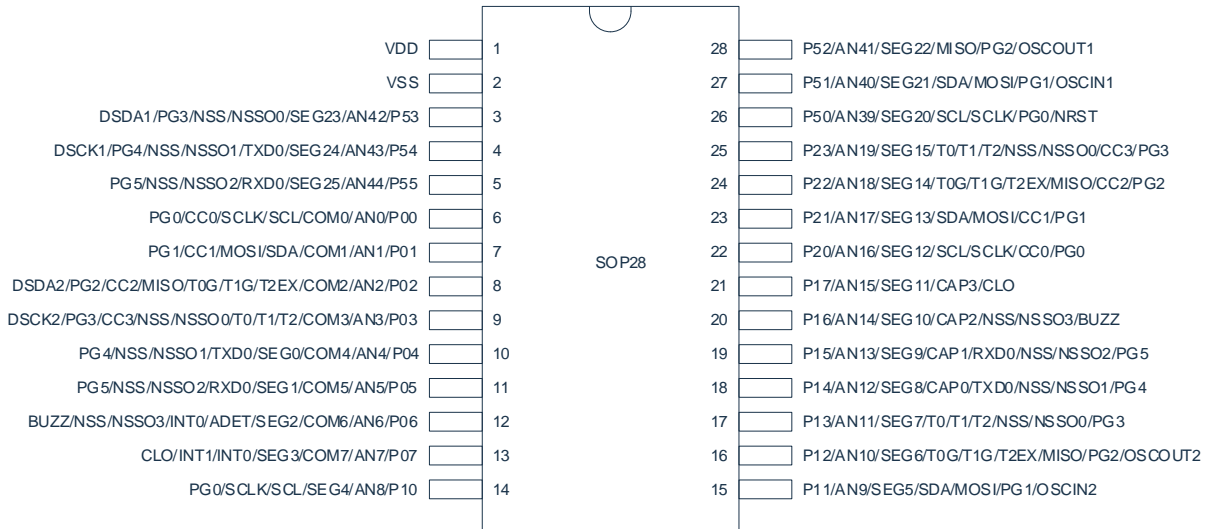
XSFR is a special register shared by the addressing space of XRAM, which mainly includes: port control register and other function control registers. Its addressing range is as follows:

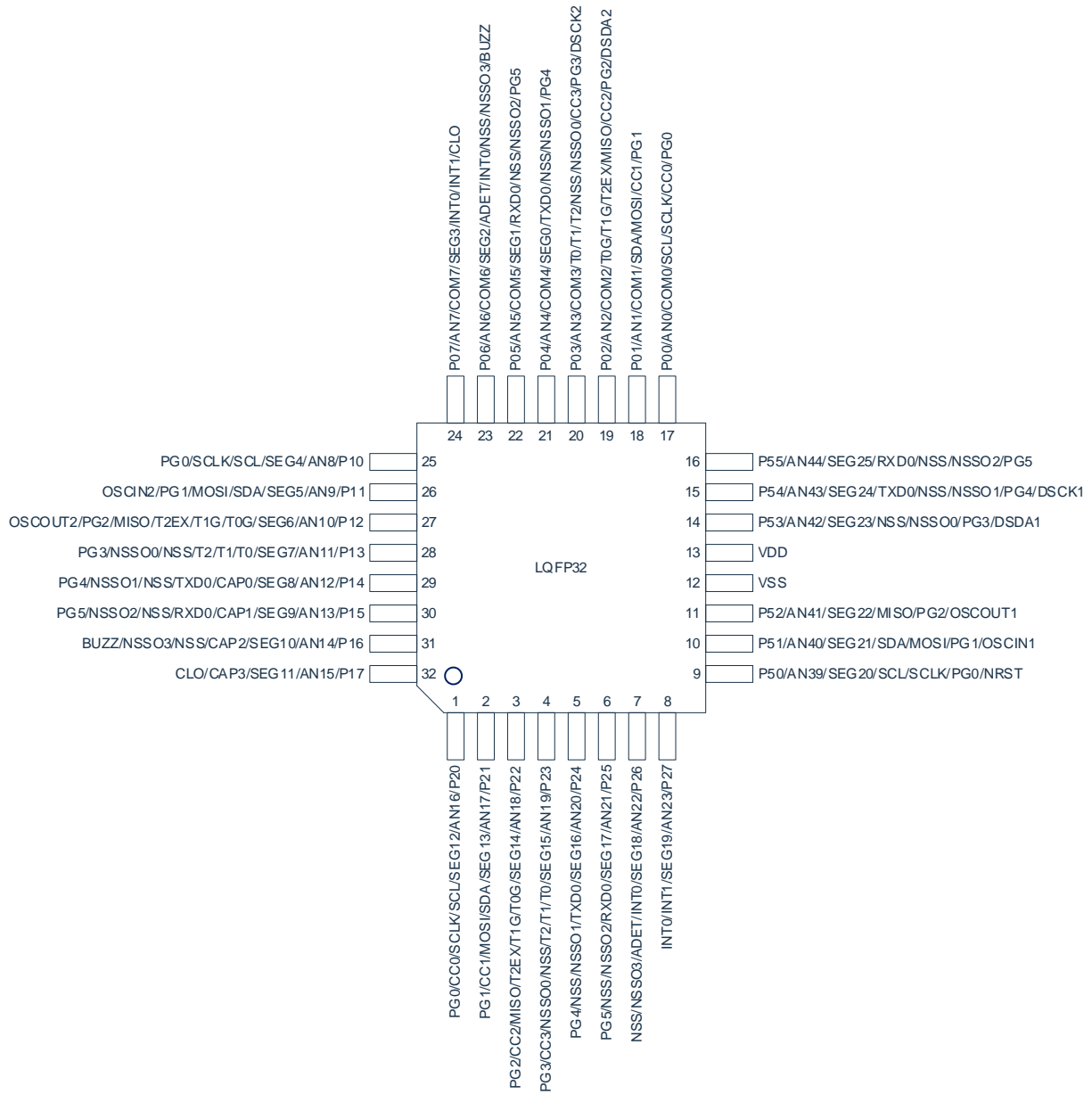


3. Pin definition

3.1 Pin description

3.1.1 CMS80F2538 Pin



3.1.2 CMS80F2539 Pin


3.2 Pin function description

Symbol description: I/O means digital input/output, I means digital input, O means digital output, AI means analog input, AO means analog output.

Pin number		Pin Function	Pin Type	Pin description
CMS80F2538	CMS80F2539			
SOP28	LQFP32			
6	17	P00	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN0	AI	ADC channel 0 input
		SCL	I/O	I2C clock input and output
		SCLK	I/O	SPI clock input and output
		CC0	O	Timer2 compare output channel 0
		PG0	O	PWM channel 0 output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
7	18	P01	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN1	AI	ADC channel 1 input
		SDA	I/O	I2C data input and output
		MOSI	I/O	SPI data master sending and slave receiving
		CC1	O	Timer2 compare output channel 1
		PG1	O	PWM channel 1 output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
8	19	P02	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN2	AI	ADC channel 2 input
		T0G	I	Timer 0 gate control input
		T1G	I	Timer 1 gate control input
		T2EX	I	Timer2falling edge automatic reload input
		MISO	I/O	SPI data master receiving and slave sending
		CC2	O	Timer2 compare output channel 2
		PG2	O	PWM channel 2 output
		DSDA2	I/O	Programming/debugging data input and output port 2
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
9	20	P03	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN3	AI	ADC channel 3 input
		T0	I	Timer0 external clock input
		T1	I	Timer1 external clock input
		T2	I	Timer2 external event or gate control input

Pin number		Pin Function	Pin Type	Pin description
CMS80F2538	CMS80F2539			
SOP28	LQFP32			
		NSS (NSSO0)	I/O	SPI slave chip select input/master chip select 1 output
		CC3	O	Timer2 compare output channel 3
		PG3	O	PWM channel 3 output
		DSCK2	I	Programming/debugging clock input port2
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
10	21	P04	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN4	AI	ADC channel 4 input
		TXD0	O	UART0 data output
		NSS (NSSO1)	I/O	SPI slave chip select input/master chip select 1 output
		PG4	O	PWM channel 4 output
		TXD1	O	UART1 data output
11	22	RXD1	I/O	UART1 Data input/synchronous mode data output
		P05	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN5	AI	ADC channel 5 input
		RXD0	I/O	UART0 Data input/synchronous mode data output
		NSS (NSSO2)	I/O	SPI slave chip select input/master chip select 2 output
		PG5	O	PWM channel 5 output
12	23	TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
		P06	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN6	AI	ADC channel 6 input
		ADET	I	ADC external trigger input
		INT0	I/O	External interrupt 0 input
		NSS (NSSO3)	I/O	SPI slave chip select input/master chip select 3 output
		BUZZ	O	Buzzer drive output
13	24	TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
		P07	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN7	AI	ADC channel 7 input
		INT0	I/O	External interrupt 0 input
		INT1	I/O	External interrupt 1 input
		CLO	O	System clock frequency division output
TXD1	O	UART1 data output		
RXD1	I/O	UART1 Data input/synchronous mode data output		

Pin number		Pin Function	Pin Type	Pin description
CMS80F2538	CMS80F2539			
SOP28	LQFP32			
14	25	P10	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN8	AI	ADC channel 8 input
		SCL	I/O	I2C clock input and output
		SCLK	I/O	SPI clock input and output
		PG0	O	PWM channel 0 output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
15	26	P11	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN9	AI	ADC channel 9 input
		SDA	I/O	I2Cdata input and output
		MOSI	I/O	SPI data master sending and slave receiving
		PG1	O	PWM channel 1 output
		OSCIN2	AI	External oscillation HSE input port 2
		TXD1	O	UART1 data output
RXD1	I/O	UART1 Data input/synchronous mode data output		
16	27	P12	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN10	AI	ADC channel 10 input
		T0G	I	Timer0 gate control input
		T1G	I	Timer1 gate control input
		T2EX	I	Timer2 falling edge automatic reload input
		MISO	I/O	SPI data master receiving and slave sending
		PG2	O	PWM channel 2 output
		OSCOU2	AO	External oscillation HSE output port 2
		TXD1	O	UART1 data output
RXD1	I/O	UART1 Data input/synchronous mode data output		
17	28	P13	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN11	AI	ADC channel 11 input
		T0	I	Timer0 external clock input
		T1	I	Timer1 external clock input
		T2	I	Timer2 external clock input
		NSS (NSSO0)	I/O	SPI slave chip select input/master chip select 0 output
		PG3	O	PWM channel 3 output
		TXD1	O	UART1 data output
RXD1	I/O	UART1 Data input/synchronous mode data output		
18	29	P14	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN12	AI	ADC channel 12 input

Pin number		Pin Function	Pin Type	Pin description
CMS80F2538	CMS80F2539			
SOP28	LQFP32			
		CAP0	I	Timer2 input capture channel 0
		TXD0	O	UART0data output
		NSS (NSSO1)	I/O	SPI slave chip select input/master chip select 1 output
		PG4	O	PWM channel 4 output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
19	30	P15	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN13	AI	ADC channel 13 input
		CAP1	I	Timer2 input capture channel 1
		RXD0	O	UART0 data input or synchronous mode data output
		NSS (NSSO2)	I/O	SPI slave chip select input/master chip select 2 output
		PG5	O	PWM channel 5 output
		TXD1	O	UART1 data output
RXD1	I/O	UART1 Data input/synchronous mode data output		
20	31	P16	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN14	AI	ADC channel 14 input
		CAP2	I	Timer2 input capture channel 2
		NSS (NSSO3)	I/O	SPI slave chip select input/master chip select 3 output
		BUZZ	O	Buzzer drive output
		TXD1	O	UART1 data output
RXD1	I/O	UART1 Data input/synchronous mode data output		
21	32	P17	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN15	AI	ADC channel 15 input
		CAP3	I	Timer2 input capture channel 3
		CLO	O	System clock frequency division output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
22	1	P20	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN16	AI	ADC channel 16 input
		SCL	I/O	I2C clock input and output
		SCLK	I/O	SPI clock input and output
		CC0	O	Timer2 compare output channel 0
		PG0	O	PWM channel 0 output
		TXD1	O	UART1 data output
RXD1	I/O	UART1 Data input/synchronous mode data output		

Pin number		Pin Function	Pin Type	Pin description
CMS80F2538	CMS80F2539			
SOP28	LQFP32			
23	2	P21	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN17	AI	ADC channel 17 input
		SDA	I/O	I2Cdata input and output
		MOSI	I/O	SPI data master sending and slave receiving
		CC1	O	Timer2 compare output channel 1
		PG1	O	PWM channel 1 output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
24	3	P22	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN18	AI	ADC channel 18 input
		T0G	I	Timer0 gate control input
		T1G	I	Timer1 gate control input
		T2EX	I	Timer2 falling edge automatic reload input
		MISO	I/O	SPI data master receiving and slave sending
		CC2	O	Timer2 compare output channel 2
		PG2	O	PWM channel 2 output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
25	4	P23	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN19	AI	ADC channel 19 input
		T0	I	Timer0 external clock input
		T1	I	Timer1 external clock input
		T2	I	Timer2 external event or gate control input
		NSS (NSSO0)	I/O	SPI slave chip select input/master chip select 0 output
		CC3	O	Timer2 compare output channel 3
		PG3	O	PWM channel 3 output
		TXD1	O	UART1data output
		RXD1	I/O	UART1Data input/synchronous mode data output
--	5	P24	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN20	AI	ADC channel 20 input
		TXD0	O	UART0data output
		NSS (NSSO1)	I/O	SPI slave chip select input/master chip select 1 output
		PG4	O	PWM channel 4 output
		TXD1	O	UART1data output
		RXD1	I/O	UART1Data input/synchronous mode data output
--	6	P25	I/O	GPIO configures input and output pull up, down and other functions through registers

Pin number		Pin Function	Pin Type	Pin description
CMS80F2538	CMS80F2539			
SOP28	LQFP32			
		AN21	AI	ADC channel 21 input
		RXD0	I/O	UART0Data input/synchronous mode data output
		NSS (NSSO2)	I/O	SPI slave chip select input/master chip select 2 output
		PG5	O	PWM channel 5 output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
--	7	P26	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN22	AI	ADC channel 22 input
		ADET	I	ADC external trigger input
		INT0	I	External interrupt 0 input
		NSS (NSSO3)	I/O	SPI slave chip select input/master chip select 3 output
		TXD1	O	UART1data output
--	8	RXD1	I/O	UART1Data input/synchronous mode data output
		P27	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN23	AI	ADC channel 23 input
		INT0	I	External interrupt 0 input
		INT1	I	External interrupt 1 input
		TXD1	O	UART1 data output
26	9	RXD1	I/O	UART1 Data input/synchronous mode data output
		P50	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN39	AI	ADC channel 39 input
		NRST	I	External reset input
		SCL	I/O	I2C clock input and output
		SCLK	I/O	SPI clock input and output
		PG0	O	PWM channel 0 output
		TXD1	O	UART1 data output
27	10	RXD1	I/O	UART1 Data input/synchronous mode data output
		P51	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN40	AI	ADC channel 40 input
		OSCIN1	AI	External oscillation HSE/LSE input port 1
		SDA	I/O	I2Cdata input and output
		MOSI	I/O	SPI data master sending and slave receiving
		PG1	O	PWM channel 1 output
		TXD1	O	UART1data output
28	11	RXD1	I/O	UART1Data input/synchronous mode data output
		P52	I/O	GPIO configures input and output pull up, down and other functions through registers

Pin number		Pin Function	Pin Type	Pin description
CMS80F2538	CMS80F2539			
SOP28	LQFP32			
		AN41	AI	ADC channel 41 input
		OSCOUT1	AO	External oscillation HSE/LSE output port 1
		MISO	I/O	SPI data master receiving and slave sending
		PG2	O	PWM channel 2 output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
3	14	P53	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN42	AI	ADC channel 42 input
		DSDA1	I/O	Programming/debugging data input and output port 1
		NSS (NSSO0)	I/O	SPI slave chip select input/master chip select 0 output
		PG3	O	PWM channel 3 output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 Data input/synchronous mode data output
4	15	P54	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN43	AI	ADC channel 43 input
		DSCK1	I	Programming/debugging clock input port1
		TXD0	O	UART 0 data output
		NSS (NSSO1)	I/O	SPI slave chip select input/master chip select 1 output
		PG4	O	PWM channel 4 output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1 data input/synchronization mode
5	16	P55	I/O	GPIO configures input and output pull up, down and other functions through registers
		AN44	AI	ADC channel 44 input
		RXD0	I/O	UART0Data input/synchronous mode data output
		NSS (NSSO2)	I/O	SPI slave chip select input/master chip select 2 output
		PG5	O	PWM channel 5 output
		TXD1	O	UART1 data output
		RXD1	I/O	UART1Data input/synchronous mode data output
1	13	VDD	P	Power supply voltage input pin
2	12	VSS/GND	P	Ground pin

3.3 GPIO features

The pins share multiple functions, and each I/O port can be configured as any digital function or designated analog function. I/O as a general GPIO port has the following characteristics:

- Configurable 2 levels of I/O output slope.
- Can read data latch status or pin status.
- Configurable rising edge, falling edge, double edge trigger interrupt.
- Configurable rising edge, falling edge, double edge interrupt to wake up the chip.
- Can be configured as normal input, pull-up input, pull-down input, push-pull output, open-drain output mode.

3.4 Pin function list

List of digital function ports:

	External input	Digital function configuration							
		0	1	2	3	4	5	6	7
P00	-	GPIO	ANA	SCL	SCLK	CC0	PG0	TXD1	RXD1
P01	-	GPIO	ANA	SDA	MOSI	CC1	PG1	TXD1	RXD1
P02	T0G/T1G/T2EX	GPIO	ANA	-	MISO	CC2	PG2	TXD1	RXD1
P03	T0/T1/T2	GPIO	ANA	-	NSS(NSS00)	CC3	PG3	TXD1	RXD1
P04	-	GPIO	ANA	TXD0	NSS(NSS01)	-	PG4	TXD1	RXD1
P05	-	GPIO	ANA	RXD0	NSS(NSS02)	-	PG5	TXD1	RXD1
P06	ADET/INT0	GPIO	ANA	-	NSS(NSS03)	BUZZ	-	TXD1	RXD1
P07	INT0/INT1	GPIO	ANA	-	-	CLO	-	TXD1	RXD1
P10	-	GPIO	ANA	SCL	SCLK	-	PG0	TXD1	RXD1
P11	-	GPIO	ANA	SDA	MOSI	-	PG1	TXD1	RXD1
P12	T0G/T1G/T2EX	GPIO	ANA	-	MISO	-	PG2	TXD1	RXD1
P13	T0/T1/T2	GPIO	ANA	-	NSS(NSS00)	-	PG3	TXD1	RXD1
P14	CAP0	GPIO	ANA	TXD0	NSS(NSS01)	-	PG4	TXD1	RXD1
P15	CAP1	GPIO	ANA	RXD0	NSS(NSS02)	-	PG5	TXD1	RXD1
P16	CAP2	GPIO	ANA	-	NSS(NSS03)	BUZZ	-	TXD1	RXD1
P17	CAP3	GPIO	ANA	-	-	CLO	-	TXD1	RXD1
P20	-	GPIO	ANA	SCL	SCLK	CC0	PG0	TXD1	RXD1
P21	-	GPIO	ANA	SDA	MOSI	CC1	PG1	TXD1	RXD1
P22	T0G/T1G/T2EX	GPIO	ANA	-	MISO	CC2	PG2	TXD1	RXD1
P23	T0/T1/T2	GPIO	ANA	-	NSS(NSS00)	CC3	PG3	TXD1	RXD1
P24	-	GPIO	ANA	TXD0	NSS(NSS01)	-	PG4	TXD1	RXD1
P25	-	GPIO	ANA	RXD0	NSS(NSS02)	-	PG5	TXD1	RXD1
P26	ADET/INT0	GPIO	ANA	-	NSS(NSS03)	-	-	TXD1	RXD1
P27	INT0/INT1	GPIO	ANA	-	-	-	-	TXD1	RXD1
P50	NSRT	GPIO	ANA	SCL	SCLK	-	PG0	TXD1	RXD1
P51	-	GPIO	ANA	SDA	MOSI	-	PG1	TXD1	RXD1
P52	-	GPIO	ANA	-	MISO	-	PG2	TXD1	RXD1
P53	-	GPIO	ANA	-	NSS(NSS00)	-	PG3	TXD1	RXD1
P54	-	GPIO	ANA	TXD0	NSS(NSS01)	-	PG4	TXD1	RXD1
P55	-	GPIO	ANA	RXD0	NSS(NSS02)	-	PG5	TXD1	RXD1

Analog port, LED port, CONFIG configuration port list:

Note: 1. The chip pins are subject to the actual chip.

	GPIO(0)		ANA(1)						CONFIG
	LEDSEG	LEDCOM	ADC						
P00	-	COM0	AN0						-
P01	-	COM1	AN1						-
P02	-	COM2	AN2						DSDA2
P03	-	COM3	AN3						DSCCK2
P04	SEG0	COM4	AN4						-
P05	SEG1	COM5	AN5						-
P06	SEG2	COM6	AN6						-
P07	SEG3	COM7	AN7						-
P10	SEG4	-	AN8						-
P11	SEG5	-	AN9						OSCIN2
P12	SEG6	-	AN10						OSCOU2
P13	SEG7	-	AN11						-
P14	SEG8	-	AN12						-
P15	SEG9	-	AN13						-
P16	SEG10	-	AN14						-
P17	SEG11	-	AN15						-
P20	SEG12	-	AN16						-
P21	SEG13	-	AN17						-
P22	SEG14	-	AN18						-
P23	SEG15	-	AN19						-
P24	SEG16	-	AN20						-
P25	SEG17	-	AN21						-
P26	SEG18	-	AN22						-
P27	SEG19	-	AN23						-
P50	SEG20	-	AN39						NRST
P51	SEG21	-	AN40						OSCIN1
P52	SEG22	-	AN41						OSCOU1
P53	SEG23	-	AN42						DSDA1
P54	SEG24	-	AN43						DSCCK1
P55	SEG25	-	AN44						-

4. Function summary

4.1 System clock

The system clock has 4 kinds of clock sources, which can be selected through the setting of the system configuration register or the user register. The system clock module has the following characteristics:

- Optional internal high-speed oscillation HIS (48MHz).
- Optional external high-speed crystal oscillator HSE (8MHz/16MHz).
- Optional external low-speed crystal oscillator LSE (32.768KHz).
- Optional internal low-speed oscillation LSI (125KHz).
- Any pair of clock sources can be switched between each other (switching between HSE and LSE is prohibited).
- The external high-speed and low-speed oscillators support the stop vibration monitoring function (SCM) when the system clock is provided.

4.2 Reset

The reset operation is used to complete the initialization of the internal circuit of the chip, so that the system starts working from a certain state. The chip has the following reset methods:

- Power-on reset.
- External reset.
- Low voltage reset.
- CONFIG state protection reset.
- Power-on configuration monitoring reset.
- Watchdog timeout reset.
- Software reset.

Any of the above reset situations requires a certain response time, and the system provides a complete reset process to ensure the smooth progress of the reset action.

4.3 Power management

4.3.1 Operating mode

The chip has 3 different working modes to meet the power consumption requirements of different applications.

- Normal working mode: MCU is in normal working state and peripherals are operating normally.
- Idle mode IDLE: MCU is in idle mode, CPU stops working, and peripherals operate normally. This mode can be awakened by any interrupt.
- Sleep mode STOP: MCU is in sleep mode, CPU stops working, and peripherals stop working. This mode can be awakened by INT0/1 interrupt, external interrupt, WUT timing wakeup, LSE timing wakeup.

4.3.2 Power supply low voltage reset (LVR)

When the power supply voltage is lower than the set detection voltage, the system resets.

There are 4 options for low voltage reset: 1.8V/2.0V/2.5V/3.5V.

4.3.3 Power supply low voltage detection (LVD)

The low voltage detection circuit compares the power supply voltage with the set voltage, and if the power supply voltage is lower than the set voltage, an interrupt request signal is generated.

Settable detection voltage range 2.0V~4.3V, A total of 8 levels are available.

4.4 Interrupt control

The chip has multiple interrupt sources and interrupt vectors. The user-settable interrupts include INT0/1, Timer0/1, Timer2, Timer3/4, WDT, LSE_Timer (SCM), PWM, I2C, SPI, UART0/1, P0/P1/P2/P5, ADC, LVD, the actual number of interrupt sources varies by product.

The chip stipulates two interrupt priority levels, which can realize two-level interrupt nesting. When an interrupt has been responded, if a high-level interrupt sends a request, the latter can interrupt the former to achieve interrupt nesting.

4.5 Timer

4.5.1 WDT timer

The watchdog timer is an on-chip timer whose clock source is provided by the system clock. The WDT timeout will generate a reset. The watchdog reset is a protection setting of the system. When the system runs to an unknown state, the watchdog can be used to reset the system, thereby avoiding the system from entering an infinite loop. The WDT timer has the following characteristics:

- 8 levels of watchdog overflow time are selectable.
- Watchdog overflow interrupt can be set.
- Watchdog overflow reset can be set.

4.5.2 Timer counter 0/1 (Timer0/1)

Timer 0 is similar in type and structure to Timer 1, and is two 16-bit up-counting timers. Timer0 has 4 working modes, Timer1 has 3 working modes, they provide basic timing and event counting operations.

In "timer mode", the timer register is incremented every 12 or 4 system cycles when the timer clock is enabled. In the "counter mode", the timing register will increase whenever it detects a falling edge on the corresponding input pin (T0 or T1).

Timer0/1 has the following features:

- Can be used as a normal timer.
- Can be used for gated timing function.
- External counting function can be realized.
- Can be used for gated counting function.
- Counter overflow interrupt.

4.5.3 Timer counter 2 (Timer2)

Timer 2 is a 16-bit timer, which can be used for various digital signal generation and event capture, such as pulse generation, pulse width modulation, pulse width measurement, etc. Timer2 has the following characteristics:

- Can be used as a normal timer.
- Can be used for gated timing function.
- External counting function can be realized.
- With reinstall prohibition, overflow auto reinstall, external pin falling edge auto reinstall function.
- Capture can be triggered by rising edge, falling edge, both edges or writing the low byte of the capture register.
- With a comparison function, this function can generate a periodic signal and a PWM waveform with a controllable duty cycle.
- Interrupts can be generated for timing, external trigger, capture, and comparison.

4.5.4 Timer 3/4(Timer3/4)

Timer 3/4 is similar to timer 0/1 and is two 16-bit timers. Timer3 has 4 working modes, and Timer4 has 3 working modes. Compared with Timer0/1, Timer3/4 only provides timing operation.

When the timer is started, the value of the register (counter) is incremented every 12 or 4 system cycles.

4.5.5 LSE timer (LSE_Timer)

The LSE timer is a 16-bit up-counting timer with a clock source from the external low-speed clock LSE. The LSE timer has the following characteristics:

- Timing function.
- 16-bit timing value can be set.
- Can work normally in sleep mode.
- An interrupt can be generated when the count value is equal to the timer value.

Timed interrupt can wake up idle mode/sleep mode.

4.5.6 Wake-up timer (WUT)

WUT wake-up timer is a 12-bit, up-counting timer used for wake-up from sleep and a clock source from the internal low-speed clock LSI. After the system enters the sleep mode, the CPU and all peripheral circuits stop working, and the internal low-speed clock LSI provides the clock for the WUT counter. WUT has the following characteristics:

- The system can be woken up regularly in sleep mode.
- Count clock can be divided by 1, 8, 32, 256.
- 12-bit timing value can be set.

4.5.7 BRT timer (BRT)

The BRT timer is a 16-bit baud rate timer whose clock source comes from the system clock. It mainly provides the clock for the UART module. BRT has the following characteristics:

- With independent control switch.
- Counting clock has 8 frequency division options.
- 16-bit up counting.

4.6 Enhanced digital peripherals

4.6.1 Cyclic redundancy check (CRC)

Cyclic Redundancy Check CRC is the most commonly used error check code in the field of data communication. Its characteristic is that the length of the information field and the check field can be arbitrarily selected. The chip CRC check unit generates a polynomial using " $X^{16}+X^{12}+X^5+1$ "(CRC16-CCITT), , specify the data to be verified through the program, so that the module is not limited to the code flash area but can be used for multi-purpose inspection.

4.6.2 BUZZER

The buzzer driver is composed of an 8-bit counter, a clock driver, and a control register. It outputs a square wave with a duty cycle of 50%, and its frequency covers a wide range. BUZZER has the following characteristics:

- With separate enable control switch.
- A total of 4 levels of system clock divider ratios of 8, 16, 32, 64 can be set.
- Output frequency 8-bit control, can be set (1~255) x 2 frequency division output.

4.6.3 PWM

PWM module supports 6 PWM generators, and the period and duty cycle can be set independently. PWM has the following characteristics:

- Support 2 kinds of waveform output in single and continuous mode.
- Support 4 control modes: independent, complementary, synchronous and group control.
- Count clock can be divided by 1, 2, 4, 8, 16.
- Support edge alignment mode.
- Support dead zone programming.
- Output polarity can be set.
- Support cycle, compare down, zero interrupt.

4.7 Communication module

4.7.1 SPI module

SPI is a fully configurable SPI master/slave device that allows users to configure the polarity and phase of the serial clock signal. SPI allows the MCU to communicate with serial peripherals, and it can also communicate between processors in a multi-host system. SPI has the following characteristics:

- Full-duplex synchronous serial data transmission.
- Support master/slave mode.
- Support multi-host system.
- System error detection.
- Support speed up to 1/4 of the system clock ($F_{SYS} \leq 24\text{MHz}$).
- Bit rate generates 1/4, 1/8, 1/16, 1/32, 1/64, 1/128, 1/256, 1/512 of the system clock.
- Support four transmission formats.
- Send/receive complete can generate interrupt.

4.7.2 I²C module

The two-wire bidirectional serial bus controller I²C provides a simple and effective connection method for data exchange between the microprocessor and the I²C bus. The I²C module has the following characteristics:

- Support 4 working methods: master sending, master receiving, slave sending, slave receiving.
- Support 2 transmission speed modes:
 - Standard (up to 100Kb/s);
 - Fast (up to 400Kb/s).
- Perform arbitration and clock synchronization.
- Support multi-host system.
- The host method supports 7-bit addressing mode and 10-bit addressing mode on the I²C bus (software support).
- The slave method supports 7-bit addressing mode on the I²C bus.
- Allows operation in a wide range of clock frequencies (built-in 8-bit timer).
- An interrupt can be generated when receiving/sending is complete.

4.7.3 UARTn module

The UARTn module contains UART0 / UART1, 2 serial ports with the same function. UARTn has the following characteristics:

- Full-duplex serial port.
- Support synchronous mode.
- Support 8-bit asynchronous transceiver mode with variable baud rate.
- Support 9-bit asynchronous transceiver mode with variable baud rate.
- Baud rate can be generated by Timer1/Timer4/Timer2/BRT module.
- Send/receive complete can generate interrupt.

4.8 Analog module

4.8.1 Analog to digital conversion (ADC)

ADC module is a 12-bit successive approximation analog-to-digital converter. The port analog input signal is connected to the input of the analog-to-digital converter after passing through the multiplexer. The analog-to-digital converter generates a 12-bit binary result according to the input analog signal and saves the result in the ADC result register. ADC has the following characteristics:

- Up to 30 external channels.
- ADC conversion clock has 8 clock frequencies to choose from.
- ADC reference voltage can choose VDD/1.2V/2.0V/2.4V/3.0V.
- A complete 12-bit conversion requires 18.5 ADC conversion cycles.
- Support external port edge, PWM trigger ADC conversion.
- Support ADC conversion result comparison output.
- Support ADC conversion completion to generate interrupt.

4.9 FLASH memory

FLASH memory includes program memory (APROM/BOOT) and non-volatile data memory (Data FLASH), It can be accessed through the relevant special function register (SFR) to realize the IAP function. FLASH memory supports the following operations:

- Byte read operation.
- Byte Write operation.
- Page erase operation.
- FLASH space CRC check operation.

4.10 Unique ID (UID)

Each chip has a 96-bit unique identification number, namely Unique identification. The UID has been set at the factory and cannot be modified by the user.

5. User Configuration

The system configuration register (CONFIG) is the FLASH option of the MCU's initial conditions, and the program cannot access and operate it. The following contents can be set through the system configuration register:

- Watchdog's working method.
- FLASH program area partition protection, code encryption, FLASH data area encryption status.
- Low voltage reset voltage.
- Disable or enable debug mode.
- Debug pin selection.
- Oscillation method, prescaler selection.
- Internal high-speed oscillator frequency division selection.
- Crystal oscillator port selection.
- Sleep wake-up waiting time.
- APROM/BOOT space.

6. Electrical parameters

6.1 Absolute maximum rating

symbol	parameter	min.	max.	unit
T_{ST}	Storage temperature	-55	150	°C
T_A	Working temperature	-40	105	°C
VDD-VSS	Power supply voltage	-0.3	5.8	V
V_{IN}	Input voltage	VSS-0.3	VDD+0.3	V
I_{DD}	VDD maximum input current	-	120	mA
I_{SS}	VSS maximum output current	-	200	mA
I_{IO}	Maximum sink current of a single IO	-	50	mA
	Maximum source current of a single IO	-	40	mA
	Maximum sink current of all IOs	-	200	mA
	Maximum source current of all IOs	-	120	mA

Note: If the operating conditions of the device exceed the range of "**absolute maximum rating**", it will cause permanent damage to the device. The function can be guaranteed only when the device works within the scope specified in the manual. The chip is at the absolute maximum rated value, which may affect the reliability of the device.

6.2 DC electrical characteristics

 $V_{DD}-V_{SS}=2.1\sim 5.5V, T_A=25^{\circ}C$

symbol	parameter	test condition	min.	typical	max.	unit
VDD	Working voltage	$F_{SYS}=48MHz$, machine cycle=2T $F_{SYS}=8MHz\sim 24MHz$, machine cycle=1T	2.1	-	5.5	V
I _{DD}	Normal mode	VDD=5V, $F_{SYS}=48MHz$, all peripherals are off machine cycle=2T	-	7	-	mA
		VDD=3V, $F_{SYS}=48MHz$, all peripherals are off machine cycle=2T	-	7	-	mA
		VDD=5V, $F_{SYS}=24MHz$, all peripherals are off machine cycle=1T	-	5	-	mA
		VDD=3V, $F_{SYS}=24MHz$, all peripherals are off machine cycle=1T	-	5	-	mA
		VDD=5V, $F_{SYS}=16MHz$, all peripherals are off machine cycle=1T	-	4	-	mA
		VDD=3V, $F_{SYS}=16MHz$, all peripherals are off machine cycle=1T	-	4	-	mA
		VDD=5V, $F_{SYS}=8MHz$, all peripherals are off machine cycle=1T	-	3	-	mA
		VDD=3V, $F_{SYS}=8MHz$, all peripherals are off machine cycle=1T	-	3	-	mA
		VDD=5V, $F_{SYS}=32.768KHz$, all peripherals are off machine cycle=1T	-	0.26	-	mA
		VDD=3V, $F_{SYS}=32.768KHz$, all peripherals are off machine cycle=1T	-	0.23	-	mA
	IDLE mode	VDD=5V, $F_{SYS}=48MHz$, all peripherals are off	-	5.5	-	mA
		VDD=3V, $F_{SYS}=48MHz$, all peripherals are off	-	5.5	-	mA
		VDD=5V, $F_{SYS}=24MHz$, all peripherals are off	-	3.5	-	mA
		VDD=3V, $F_{SYS}=24MHz$, all peripherals are off	-	3.5	-	mA
		VDD=5V, $F_{SYS}=16MHz$, all peripherals are off	-	2.5	-	mA
		VDD=3V, $F_{SYS}=16MHz$, all peripherals are off	-	2.5	-	mA
		VDD=5V, $F_{SYS}=8MHz$, all peripherals are off	-	2	-	mA
		VDD=3V, $F_{SYS}=8MHz$, all peripherals are off	-	2	-	mA
		VDD=5V, $F_{SYS}=32.768KHz$, all peripherals are off	-	0.26	-	mA
		VDD=3V, $F_{SYS}=32.768KHz$, all peripherals are off	-	0.23	-	mA
ISLEEP1	sleep current	all peripherals are off, LSE timer enable	-	20	-	uA
ISLEEP2	sleep current	all peripherals are off, LSI, WUT timer enable	-	7	-	uA
ISLEEP3	sleep current	all peripherals are off	-	6	-	uA
I _{LI}	Input leakage	-	-	-	0.1	uA
V _{IL}	Input low level	-	VSS	-	0.3VDD	V
V _{IH}	Input high level	-	0.7VDD	-	VDD	V
V _{OL}	Low output voltage	VDD=5V, I _{OL1} =18mA	-	-	0.4	V
		VDD=3V, I _{OL1} =12mA	-	-	0.4	V
V _{OH}	Output high voltage	VDD=5V, I _{OH1} =35mA	3.5	-	-	V
		VDD=3V, I _{OH1} =13.5mA	2.1	-	-	V
R _{PH}	Pull-up resistor	-	-	32	-	KΩ
R _{PL}	Pull-down resistor	-	-	32	-	KΩ

6.3 AC electrical parameter

6.3.1 Power-up and power-down operations

$T_A=25^{\circ}\text{C}$, does not include 32.768K crystal oscillator start-up time

symbol	parameter	test condition	min.	typical	max.	unit
T_{RESET}	Reset time	VDD=5V	-	16	-	ms
TVDDR	VDD rise rate	VDD=5V	20	-	-	us/V
TVDDF	VDD fall rate	VDD=5V	20	-	-	us/V

6.3.2 External oscillator

symbol	parameter	test condition	min.	typical	max.	unit
V_{HSE}	Working voltage	F=8/16MHz, $C_{\text{XT}}=0\text{-}47\text{pF}$	2.1	-	5.5	V
V_{LSE}	Working voltage	F=32.768KHz, $C_{\text{XT}}=10\text{-}22\text{pF}$	2.1	-	5.5	V

6.3.3 Internal oscillator

VDD=2.1V-5.5V

symbol	parameter	test condition	Frequency error	min.	typical	max.	unit
F_{HSI}	Internal high speed 48MHz	$T_A=25^{\circ}\text{C}$	$\pm 1\%$	-	48	-	MHz
		$T_A=-20^{\circ}\text{C}$ to 85°C	$\pm 2\%$	-	48	-	MHz
		$T_A=-40^{\circ}\text{C}$ to 105°C	$\pm 3\%$	-	48	-	MHz
F_{LSI}	Internal low speed 125KHz	$T_A=25^{\circ}\text{C}$	$\pm 20\%$	-	125	-	KHz
		$T_A=-40^{\circ}\text{C}$ to 105°C	$\pm 50\%$	-	125	-	KHz

6.3.4 Low voltage reset electrical parameter

symbol	parameter	min.	typical	max.	unit
V_{LVR1}	Low voltage detection threshold 1.8V	1.65	1.8	1.95	V
V_{LVR2}	Low voltage detection threshold 2.0V	1.85	2.0	2.15	V
V_{LVR3}	Low voltage detection threshold 2.5V	2.35	2.5	2.65	V
V_{LVR4}	Low voltage detection threshold 3.5V	3.35	3.5	3.65	V

6.3.5 LVD electrical parameter

symbol	parameter	min.	typical	max.	unit
V_{LVD1}	Low voltage detection threshold 2.00V	1.90	2.00	2.10	V
V_{LVD2}	Low voltage detection threshold 2.20V	2.10	2.20	2.30	V
V_{LVD3}	Low voltage detection threshold 2.40V	2.30	2.40	2.50	V
V_{LVD4}	Low voltage detection threshold 2.70V	2.60	2.70	2.80	V
V_{LVD5}	Low voltage detection threshold 3.00V	2.90	3.00	3.10	V
V_{LVD6}	Low voltage detection threshold 3.70V	3.60	3.70	3.80	V
V_{LVD7}	Low voltage detection threshold 4.00V	3.90	4.00	4.10	V
V_{LVD8}	Low voltage detection threshold 4.30V	4.20	4.30	4.40	V

6.4 FLASH electrical parameter

symbol	parameter	test condition	min.	typical	max.	unit
V_F	FLASH working voltage	-	2.1	-	5.5	V
T_F	FLASH working temperature	-	-40	27	105	°C
$N_{ENDURANCE}$	Number of erasing and writing	Program FLASH	20000	-	-	Cycle
		Data Flash	100,000			Cycle
T_{RET}	Data retention time	25°C	100	-	-	year
T_{ERASE}	Sector erase time	-	-	1.5	-	ms
T_{WRITE}	Byte write time	-	-	50	-	us
I_{DD1}	Read current	-	-	-	2.5	mA
I_{DD2}	Programming current	-	-	-	3.6	mA
I_{DD3}	Erase current	-	-	-	2	mA

6.5 Analog characteristics

6.5.1 BANDGAP electrical characteristics

symbol	parameter	test condition	min.	typical	max.	unit
V _{BG}	Internal reference 1.2V	VDD=2.1~5.5V, T _A =25°C	1.188	1.2	1.212	V
		VDD=2.1~5.5V, T _A =-20°C to 85°C	1.182	1.2	1.218	V
		VDD=2.1~5.5V, T _A =-40°C to 105°C	1.176	1.2	1.224	V

6.5.2 ADC electrical characteristics

 T_A=25°C

symbol	parameter	min.	typical	max.	unit	
V _{AVDD}	ADC 工作电压	2.5	-	5.5	V	
V _{REF1}	Reference voltage 1	-	V _{AVDD}	-	V	
V _{REF2}	Reference voltage 2 ^(Note1, Note2) (Not V _{BG})	1.185	1.2	1.215	V	
V _{REF3}	Reference voltage 3 ^(Note2)	1.985	2.0	2.015	V	
V _{REF4}	Reference voltage 4 ^(Note2)	2.385	2.4	2.415	V	
V _{REF5}	Reference voltage 5 ^(Note2)	2.985	3.0	3.015	V	
V _{ADI}	Input voltage	0	-	V _{REF}	V	
N _R	resolution	12			Bit	
DNL	Differential nonlinearity error (V _{REF} =V _{AVDD} =5V, T _{ADCK} =0.5us)	±2			LSB	
INL	Integral nonlinearity error (V _{REF} =V _{AVDD} =5V, T _{ADCK} =0.5us)	±4			LSB	
T _{ADCK}	ADC clock cycle	V _{REF} =VDD=5V	0.5	-	-	us
		V _{REF} =V _{REF2}	32	-	-	us
		V _{REF} =V _{REF3} /V _{REF4} /V _{REF5}	2	-	-	us
T _{ADC}	ADC conversion time	-	18.5	-	T _{ADCK}	
F _s	Sampling rate (V _{REF} =V _{AVDD} =5V)	100			Ksps	

 Note1: When V_{REF}=V_{REF2}, the precision is 8bit.

 Note2: Test Condition: T_A=25°C, V_{AVDD}=5.0V.

6.6 EMC Characteristics

6.6.1 EFT electrical characteristics

symbol	parameter	test condition	level
V _{EFTB}	Fast transient voltage burst limits to be applied through 0.1uF(capacitance) on VDD and VSS pins to induce a functional disturbance	T _A = + 25°C, F _{SYS} =48MHz, conforms to IEC 61000-4-4	4B

Note: The electrical fast transient (EFT) immunity performance is closely related to system design (including power supply structure, circuit design, layout, chip configuration, program structure, etc.). The EFT parameter in the above table is the result measured on the CMS internal test platform, and is not suitable for all application environments. The test data is only for reference. All aspects of system design may affect EFT performance. In applications with high EFT performance requirements, attention should be paid to avoid interference sources affecting system operation when designing. It is recommended to analyze interference paths and optimize the design to achieve the best anti-interference performance.

6.6.2 ESD Electrical characteristics

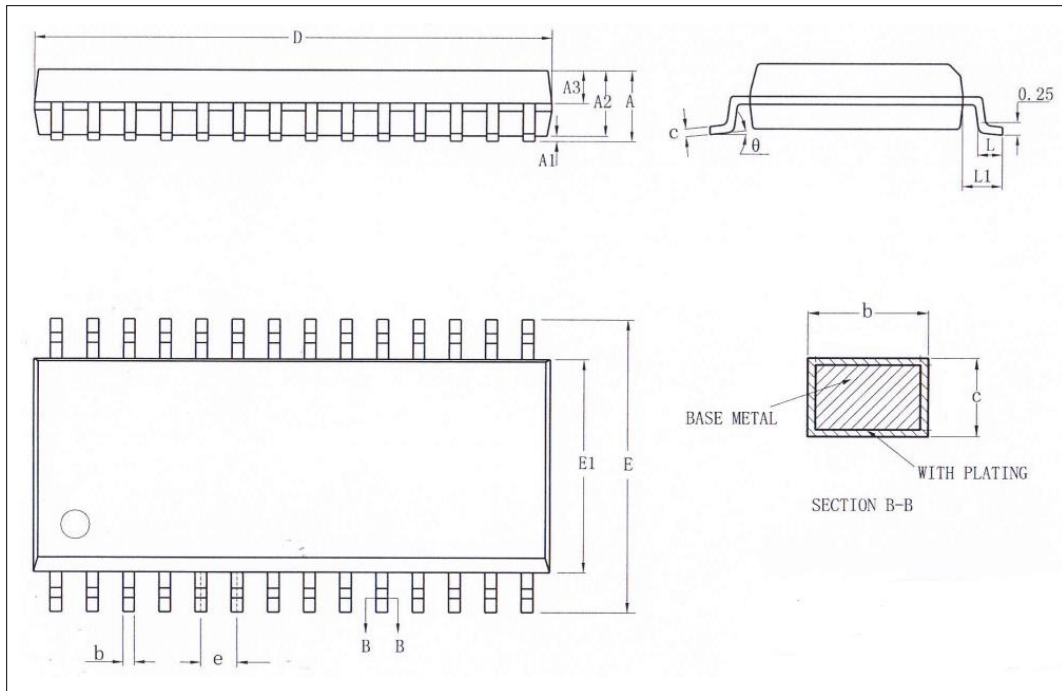
symbol	parameter	test condition	level
V _{ESD}	Electrostatic discharge (Human body model HBM)	T _A = + 25°C, JEDEC EIA/JESD22- A114	3B
	Electrostatic discharge (Machine discharge mode MM)	T _A = + 25°C, JEDEC EIA/JESD22- A115	C

6.6.3 Latch-Up electrical characteristics

symbol	parameter	test condition	Test type
LU	Static latch-up class	JEDEC STANDARD NO.78D NOVEMBER 2011	Class I (T _A = +25°C)

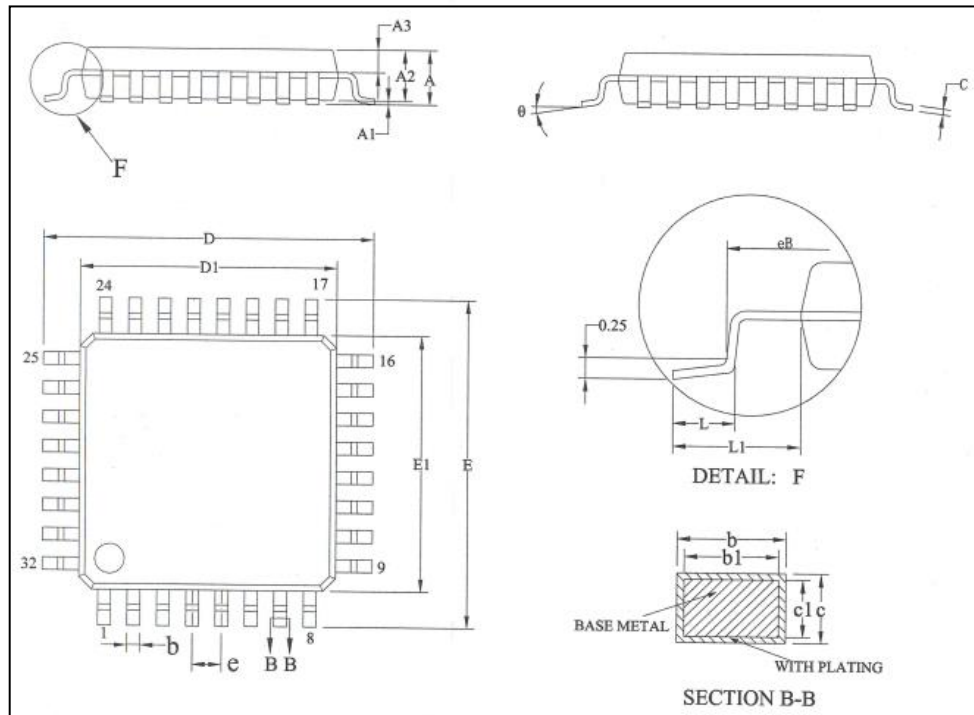
7. Package information

7.1 SOP28



Symbol	Millimeter		
	Min	Nom	Max
A	-	-	2.65
A1	0.10	-	0.30
A2	2.24	-	2.44
A3	0.97	1.02	1.07
b	0.39	-	0.47
c	0.25	-	0.30
D	17.90	18.00	18.10
E	10.10	10.30	10.50
E1	7.40	7.50	7.60
e	1.27BSC		
L	0.70	-	1.01
L1	1.40REF		
θ	0	-	8°

Caution: Package dimensions do not include mold flash or gate burrs.

7.2 LQFP32


Symbol	Millimeter		
	Min	Nom	Max
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
A3	0.59	0.64	0.69
b	0.32	-	0.43
b1	0.31	0.35	0.39
c	0.13	-	0.18
c1	0.12	0.13	0.14
D	8.80	9.00	9.20
D1	6.90	7.00	7.10
E	8.80	9.00	9.20
E1	6.90	7.00	7.10
eB	8.10	-	8.25
e	0.80BSC		
L	0.45	-	0.75
L1	1.00REF		
θ	0	-	7°

Caution: Package dimensions do not include mold flash or gate burrs.

8. Revision History

Revision	Date	Modify content
V1.00	May 2020	Initial verison
V1.01	Jun 2021	Modify the function of some pins
V1.02	Dec 2021	Update the Flash electrical parameters
V1.0.3	May 2022	1) 6.1 Absolute maximum rating: add limit parameter notes 2) 6.3.1 Power-up and power-down operations: adjust parameters 3) 6.3.3 Internal oscillator: adjust parameters 4) 6.5.1 BANDGAP electrical characteristics: detailed parameters 5) 6.5.2 ADC electrical characteristics: ADC clock cycle is described according to different reference voltages 6) Update 6.6 EMC Characteristics
V1.0.4	Sep 2023	1) Modify the 6.4 FLASH electrical parameter 2) Modified SOP28/LQFP32 package dimensions 3) Revised the cover page
V1.0.5	Dec 2024	Added Remarks in section 6.5.2